

C1808X332JBGACTU

Aliases (C1808X332JBGAC7800)

SMD Comm COG HV Flex, Ceramic, 3300 pF, 5%, 630 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1808



Click here for the 3D model.

Dimensions		
Chip Size	1808	
L	4.7mm +/-0.5mm	
W	2mm +/-0.2mm	
Т	1.4mm +/-0.15mm	
В	0.7mm +/-0.35mm	

Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	
Packaging Quantity	1000	

General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	62 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3300 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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